MultiPrep 200
Copper Adhesion Promoter

Superior Bonding to Soldermask, Dry Film and Photoresist.

The MultiPrep 200 adhesive promoter process creates an ideal surface for the adhesion of soldermask, dry film and liquid photo resist on copper. MultiPrep 200 eliminates the need for pumice and brush scrubbing, providing a uniform copper surface topography for unsurpassed bonding consistency.

MultiPrep 200 delivers a rough micro-roughened surface that is excellent for solder mask adhesion to microvias and ultra-fine features, as well as creating a strong, reliable bond between via fill and PTH copper.

The MultiPrep 200 chemistry provides an optimized copper surface roughening that is perfect for soldermask application. In addition, it is compatible with all final finish chemistries, including ENIG, silver, OSP and immersion tin.

Choose MultiPrep 200 for unparalleled copper adhesion to all organic thermal fills, coatings and films.

KEY FEATURES

• Easily controllable process with a long bath life
• Creates a high adhesion microetch topography
• Provides an exceptionally uniform appearance
MultiPrep 200
Copper Adhesion Promoter

Customized Micro Roughening Process That Delivers Superior Soldermask and Photoresist Adhesion

MultiPrep 200 results from decades of MacDermid Enthone experience with etching copper for optimized compatibility with our many other processes. When you use MultiPrep 200, you can be assured that our processes will perform reliably and durably, resulting in approval at all levels of the supply chain.

Delivering a rough, microetched surface that is ideal for microvias and ultra-fine structures on complex circuit boards, MultiPrep 200 is perfect for with all surface finishes, and provides ultimate uniformity and clean, continuous cosmetics.

MultiPrep 200

Traditional Microetch

SEM at 5K x,
Zygo results: Ra=0.58 µm
Rz=5.2µm

Uniform rough topography
for bonding solder mask
and photoresist (perfect
tape-test adhesion even
after immersion tin)

SEM at 5K x,
Zygo results: Ra=0.03 µm
Rz=0.36µm

Solder mask lifting in tape
test after immersion tin
exposure

Various MultiPrep 200 Applications

Preclean for dryfilm and liquid photoresist

Microetch for solder mask

Roughen microvias for resin plugging

MacDermid Enthone is a product brand of MacDermid Alpha Electronics Solutions.